

# BERGQUIST® LIQUI FORM TLF 10000

**Thermally Conductive Gel Interface Material For High Power Industrial Infrastructure Devices**

Electronic systems responsible for the processing and movement of data – from 5G telecom and EV infrastructure to AI and industrial automation – are incorporating higher-power devices in increasingly dense designs to meet high bandwidth expectations. To efficiently manage heat dissipation and accommodate mass production demands for higher operating temperature devices, Henkel has developed BERGQUIST® LIQUI FORM TLF 10000. The pre-cured, one-part liquid gel provides thermal conductivity of 10.0 W/m-K with reliable vertical gap stability and characteristics that support volume manufacturing.



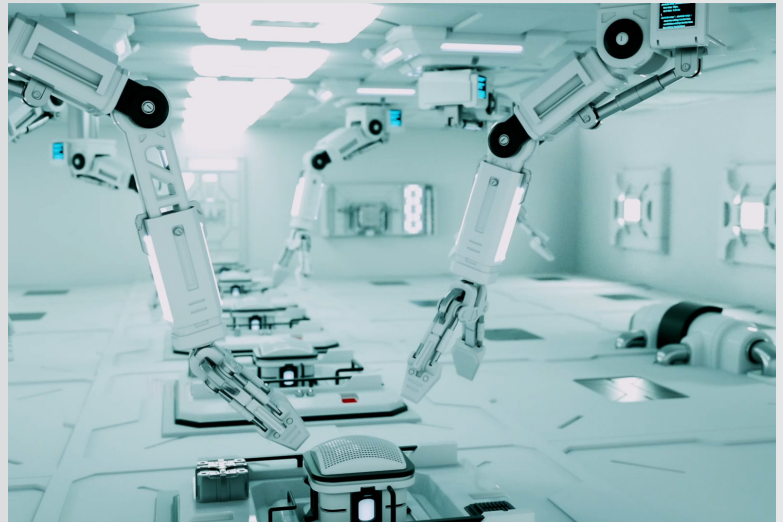
## Key Benefits

- High thermal conductivity 10.0 W/m-K for high-performance component cooling efficiency
- Reliable vertical gap stability for gaps ranging from 0.5 to 1.5 mm based on 2,350 hrs. of testing at -40/+125°C
- Dispensing speeds as fast as 22 g/min. with excellent flow rate stability for high volume manufacturing
- Provides supply chain simplicity as a single material can be used for various devices and differing volumes
- Easy handling and processing; one-part, pre-cured formulation requires no mixing
- Very low assembly stress reduces opportunities for component damage



## Product Properties

Technology	Silicone
Appearance	Red Gel
Thermal Conductivity (W/mK)	10
Dispense Rate (grams/minute)	22
Operating Temperature Range	-60 to 200°C
Volume Resistivity, 500 V DC, ASTM D257 ( $\Omega$ -meter)	$9.0 \times 10^{+13}$
UL Flammability Rating	UL 94 V-0



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